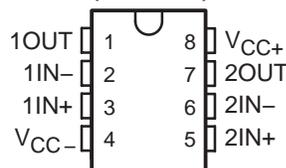


RC4560 DUAL AUDIO OPERATIONAL AMPLIFIER

SLOS457 – JANUARY 2005

- Operating Voltage . . . $\pm 2\text{ V}$ to $\pm 18\text{ V}$
- Low Noise Voltage . . . $1.2\ \mu\text{Vrms}$ (Typ)
- Wide GBW . . . 15 MHz (Typ)
- Low THD . . . 0.05% (Typ)
- Slew Rate . . . $5.5\text{V}/\mu\text{sec}$ (Typ)
- Suitable for Applications Such as Audio Preamplifier, Active Filter, Headphone Amplifier, Industrial Measurement Equipment

D (SOIC), DGK (VSSOP/MSOP), P (PDIP),
OR PW (TSSOP) PACKAGE
(TOP VIEW)



description/ordering information

The RC4560 is a high-gain, wide-bandwidth, dual operational amplifier capable of driving 20 V peak-to-peak into $400\text{-}\Omega$ loads. The RC4560 combines many of the features of the RC4558, but with wider bandwidth and higher slew rate, making this device ideal for active filters, data and telecommunications, and many instrumentation applications.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	MSOP/VSSOP (DGK)	Reel of 2500	RC4560IDGKR	PREVIEW
		Reel of 250	RC4560IDGKT	
	PDIP (P)	Tube of 50	RC4560IP	RC4560IP
	SOIC (D)	Tube of 75	RC4560ID	R4560I
		Reel of 2500	RC4560IDR	
	TSSOP (PW)	Tube of 150	RC4560IPW	R4560I
Reel of 2000		RC4560IPWR		

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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recommended operating conditions

		MIN	MAX	UNIT
V _{CC+}	Supply voltage	2	16	V
V _{CC-}		-2	-16	
V _{ID}	Differential input voltage		±30	V
V _{ICR}	Input common mode range	-14	14	V
T _A	Operating free-air temperature range	-40	85	°C

electrical characteristics, V_{CC±} = ±15 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{IO}	Input offset voltage	R _S ≤ 10 kΩ		0.5	6	mV
I _{IO}	Input offset current			5	200	nA
I _{IB}	Input bias current			40	500	nA
A _{VD}	Large-signal differential voltage amplification	R _L ≥ 2 kΩ, V _O = ±10 V	86	100		dB
r _i	Input resistance		0.3	5		MΩ
V _O	Output voltage swing	R _L ≥ 2 kΩ I _O = 25 mA	±12 ±10	±14 ±12.5		V
V _{ICR}	Common-mode input voltage range		±12	±14		V
CMRR	Common-mode rejection ratio	R _S ≤ 10 kΩ	70	90		dB
k _{SVR} †	Supply-voltage rejection ratio	R _S ≤ 10 kΩ	76.5	90		dB
I _{CC}	Supply current (all amplifiers)			4.3	5.7	mA

† Measured with V_{CC±} differentially varied simultaneously from ±4 V to ±15 V

operating characteristics, V_{CC±} = ±15 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SR	Slew rate at unity gain			5.5		V/μs
GBW	Gain bandwidth product			15		MHz
THD	Total harmonic distortion	V _O = 5 V, R _L = 2 kΩ, f = 1 kHz, A _{VD} = 20 dB		0.05		%
V _n	Equivalent input noise voltage	RIAA, R _S ≤ 2 kΩ, 30 kHz LPF		1.2		μVrms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
RC4560ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4560IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4560IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4560IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4560IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4560IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4560IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
RC4560IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
RC4560IPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4560IPWE4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4560IPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4560IPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4560IPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4560IPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

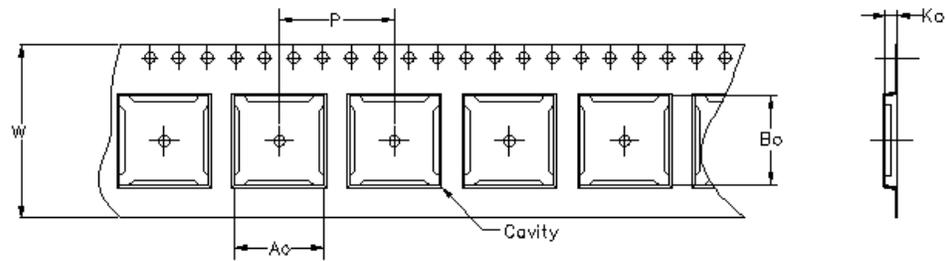
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is

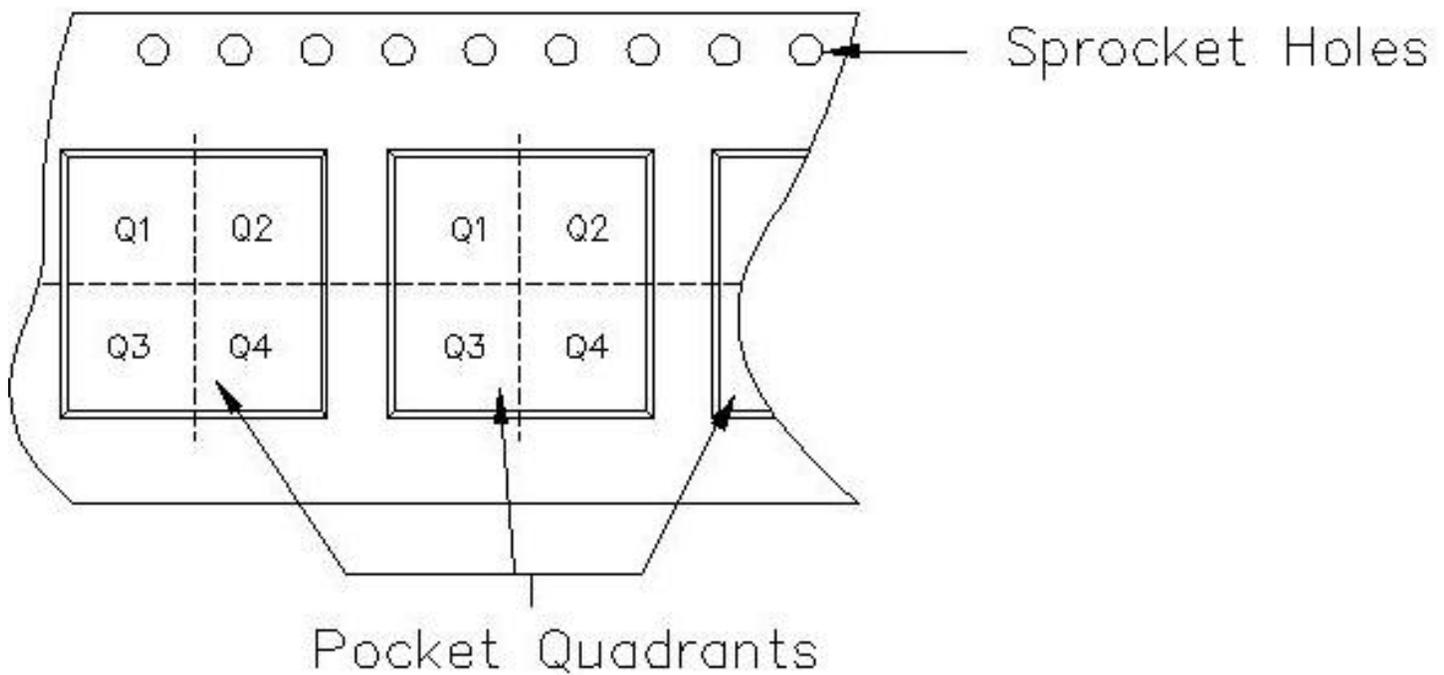
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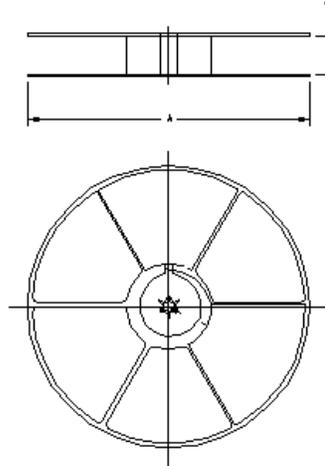
Carrier tape design is defined largely by the component length, width, and thickness.

A_o = Dimension designed to accommodate the component width.
B_o = Dimension designed to accommodate the component length.
K_o = Dimension designed to accommodate the component thickness.
W = Overall width of the carrier tape.
P = Pitch between successive cavity centers.



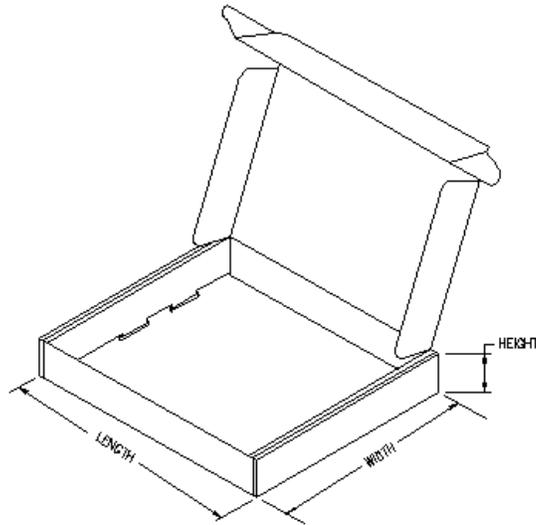
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
RC4560IDR	D	8	FMX	330	12	6.4	5.2	2.1	8	12	Q1
RC4560IPWR	PW	8	MLA	330	12	7.0	3.6	1.6	8	12	Q1



TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
RC4560IDR	D	8	FMX	338.1	340.5	20.64
RC4560IPWR	PW	8	MLA	338.1	340.5	20.64



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